

PARTICLE PRODUCTION APPARATUS, PARTICLE PRODUCTION METHOD AND METHOD
FOR PRODUCING SEMICONDUCTOR ENCAPSULATING RESIN COMPOSITION

ABSTRACT

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A particle production apparatus 1 includes a processing
section 3 in which a processing liquid is allowed to adhere to a
surface of each of inorganic particles contained in a powder
material, a chamber 4 connected to the processing section 3 at a
10 downstream side thereof in which the powder material is separated
from gas carrying the powder material, a powder material supply
device 50 having a supply portion 5 and a supply unit 6 for supplying
the powder material and the like into the processing section 3, and a
processing liquid spraying device 70 having a nozzle 7, a pump 8, a
15 supply unit 9 for supplying the processing liquid, a high-pressure
gas (air) generating unit 11 and the like. The processing liquid
spraying device 70 is configured to spray the processing liquid as
droplets onto the powder material just after the powder material
being supplied into the processing section 3. Preferably, a volume
20 of the processing section 3 is smaller than a volume of the chamber
4.

Figure 2 accompanies the abstract.